

Specification for Approval

 Date: 2020/10/9


Certificate of Green Partner

Customer : _____

 TAI-TECH P/N: HCB1005KF-221T10

CUSTOMER P/N: _____

DESCRIPTION: _____

QUANTITY: _____ pcs

REMARK:		
Customer Approval Feedback		

西北臺慶科技股份有限公司
TAI-TECH Advanced Electronics Co., Ltd

西北臺慶科技股份有限公司
 TAI-TECH Advanced Electronics Co., Ltd
 Headquarter:
 NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI,
 TAO-YUAN HSIEN, TAIWAN, R.O.C.
 TEL: +886-3-4641148 FAX: +886-3-4643565
 http://www.tai-tech.com.tw
 E-mail: sales@tai-tech.com.tw

Sales Dep.

APPROVED	CHECKED
管哲頌 Eric Guan	蒯青榮

Office:
 深圳辦公室
 11BC, Building B Fortune Plaza, NO.7002, Shennan Avenue, Futian
 District Shenzhen
 TEL: +86-755-23972371 FAX: +86-755-23972340

臺慶精密電子(昆山)有限公司
 TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD
 SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN,
 JIANG-SU, CHINA
 TEL: +86-512-57619396 FAX: +86-512-57619688
 E-mail: sales@tai-tech.cn

R&D Center

APPROVED	CHECKED	DRAWN
鄧福興	浦冬生	王俞琴

慶邦電子元器件(泗洪)有限公司
 TAIPAQ ELECTRONICS (SIHONG) CO., LTD
 JIN SHA JIANG ROAD, CONOMIC DEVELOPMENT ZONE SIHONG,
 JIANGSU, CHINA.
 TEL: +86-527-88601191 FAX: +86-527-88601190
 E-mail: sales@taipaq.cn

Ferrite Chip Bead(Lead Free)	HCB1005KF-221T10
-------------------------------------	------------------

ECN HISTORY LIST					
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉玲
2.0	14/01/24	變更電鍍錫層厚度 3.0um min. => 3.5um min.	楊祥忠	羅培君	張嘉玲
3.0	14/03/20	修正包裝帶圖示	楊祥忠	羅培君	張嘉玲
4.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲
4.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲
5.0	16/01/26	增訂可靠度 Thermal shock: (Bead) Step3 : 125±2℃ 30±5min	楊祥忠	詹偉特	張嘉玲
6.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲
7.0	20/08/01	更新 Reflow 依 IPC EDEC J-STD-020E	鄧福興	浦冬生	王俞琴
備 註					

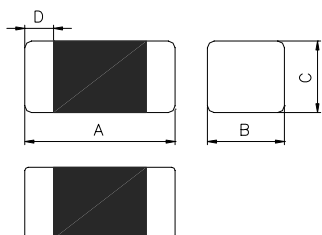
Ferrite Chip Bead(Lead Free) HCB1005KF-221T10

1.Features

1. Monolithic inorganic material construction.
2. Closed magnetic circuit avoids crosstalk.
3. Suitable for reflow soldering.
4. Shapes and dimensions follow E.I.A. spec.
5. Available in various sizes.
6. Excellent solder ability and heat resistance.
7. High reliability.
8. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.
10. Operating Temperature: -55~+125°C (Including self-temperature rise)



2.Dimensions



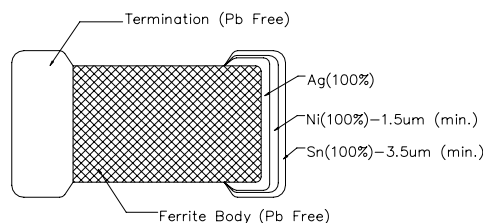
Chip Size	
A	1.00±0.10
B	0.50±0.10
C	0.50±0.10
D	0.25±0.10

Units: mm

3.Part Numbering



- A: Series
- B: Dimension L x W
- C: Material Lead Free Material
- D: Impedance 221=220Ω
- E: Packaging T=Taping and Reel, B=Bulk(Bags)
- F: Rated Current 10=1000mA

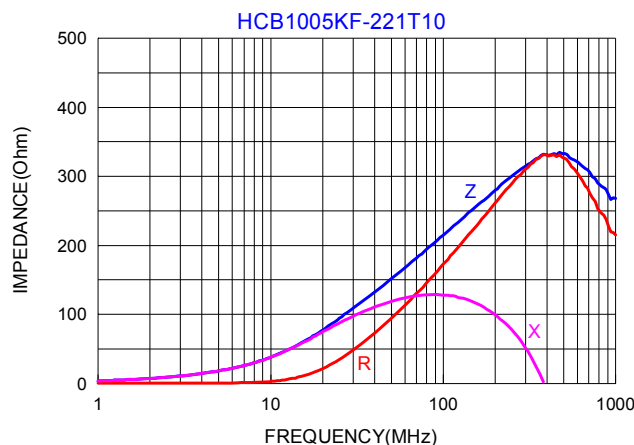


4.Specification

Tai-Tech Part Number	Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
HCB1005KF-221T10	220±25%	60mV/100M	0.20	1000

- Rated current: based on temperature rise test
- In compliance with EIA 595

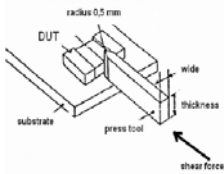
■ Impedance-Frequency Characteristics



www.tai-tech.com.tw

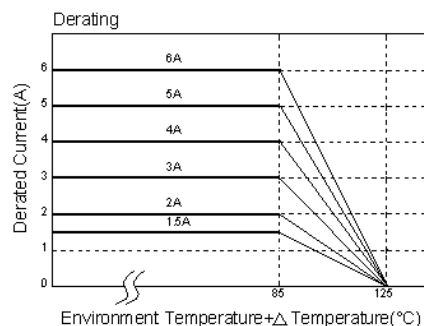
5. Reliability and Test Condition

Item	Performance					Test Condition															
Series No.	FCB	FCM	HCB	GHB	FCA	--															
Operating Temperature	-55~+125°C (Including self-temperature rise)					--															
Transportation Storage Temperature	-55~+125°C (on board)					For long storage conditions, please see the Application Notice															
Impedance (Z)	Refer to standard electrical characteristics list					Agilent4291 Agilent E4991 Agilent4287 Agilent16192															
DC Resistance						Agilent 4338															
Rated Current						DC Power Supply Over Rated Current requirements, there will be some risk															
Temperature Rise Test	Rated Current < 1A ΔT 20°CMax Rated Current ≥ 1A ΔT 40°CMax					1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.															
Life test	Appearance: no damage.					Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature: 125±2°C Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs.															
Load Humidity	Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration:1000hrsMin.Bead:with100%ratedcurrent Inductance: with 10% rated current Measured at room temperature after placing for 24±2 hrs.															
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1: -55±2°C 30±5 min. Step2: 25±2°C ≅0.5min Step3: +125±2°C 30±5min. Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.															
Vibration	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz ~ 2KHz ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) .															
Bending	Appearance : No damage. Impedance : within±10% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min.															
Shock	Appearance : No damage. Impedance : within±10% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value					Test condition: <table border="1"> <thead> <tr> <th>Type</th> <th>Peak Value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (V)/ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)/ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (V)/ft/sec																	
SMD	50	11	Half-sine	11.3																	
Lead	50	11	Half-sine	11.3																	
Solderability	More than 95% of the terminal electrode should be covered with solder.					a.Method B, 4 hrs @155°C dry heat @235°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min)@ 260°C±5°C Test time: 30 +0/-0.5 seconds.															

Item	Performance	Test Condition						
Resistance to Soldering Heat	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Number of heat cycles: 1 <table border="1"> <thead> <tr> <th>Temperature (°C)</th> <th>Time (s)</th> <th>Temperature ramp/immersion and emersion rate</th> </tr> </thead> <tbody> <tr> <td>260 ±5 (solder temp)</td> <td>10 ±1</td> <td>25mm/s ±6 mm/s</td> </tr> </tbody> </table> Depth: completely cover the termination	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s
		Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate				
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s						
Terminal strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	 Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Component mounted on a PCB apply a force >0805inch(2012mm):1kg <=0805inch(2012mm):0.5kg to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shock the component being tested.						

****Derating Curve**

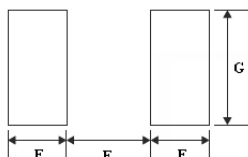
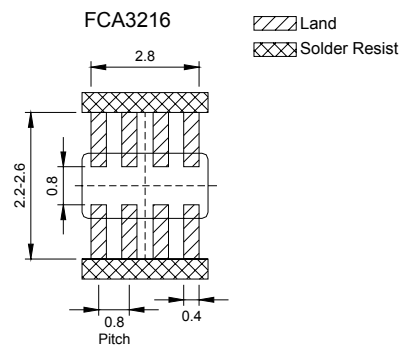
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over 85°C, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



6.Soldering and Mounting

6-1. Recommended PC Board Pattern

Series	Type	Chip Size				Land Patterns For Reflow Soldering		
		A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
HCB	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	1.00	1.45
GHB		2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30			
FCI	3216	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	1.05	2.20	1.80
FHI	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
FCH	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
HCI	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

6-2.1 IR Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

6-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4-5sec.

Fig.1 IR Soldering Reflow

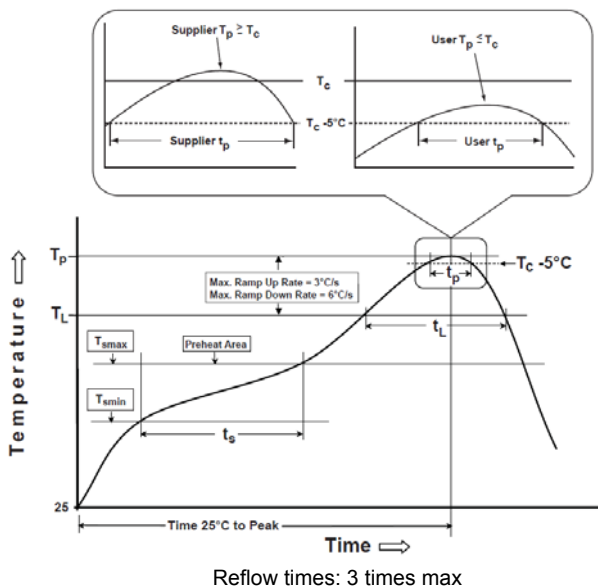


Fig.2 Iron soldering temperature profiles

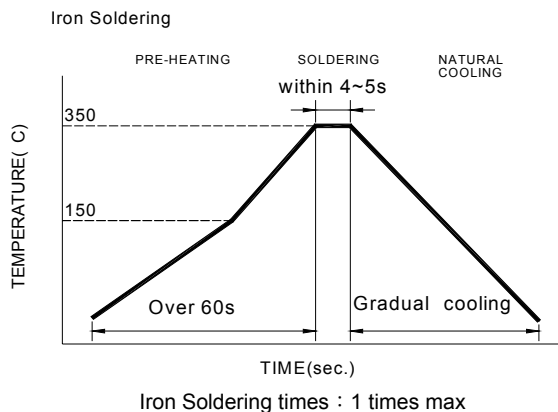


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min(T_{smin})	150°C
-Temperature Max(T_{smax})	200°C
-Time(t_s)from(T_{smin} to T_{smax})	60-120seconds
Ramp-up rate(T_l to T_p)	3°C/second max.
Liquidus temperature(T_l)	217°C
Time(t_l)maintained above T_l	60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate(T_p to T_l)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.
For user (customer) **Tp** should be equal to or less than **Tc**.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

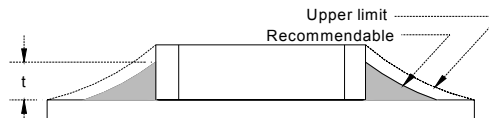
	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ◦

6-2.3 Solder Volume:

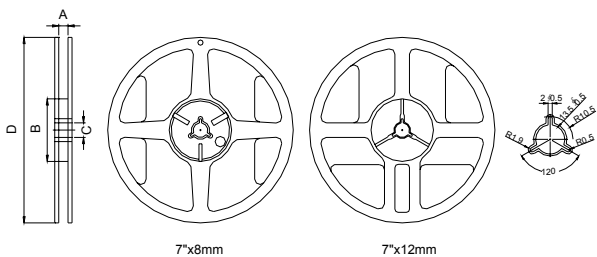
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7.Packaging Information

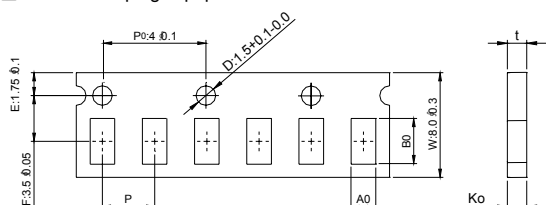
7-1. Reel Dimension



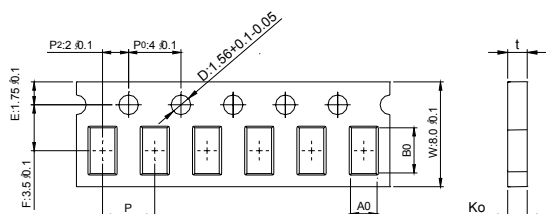
Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

7-2.1 Tape Dimension / 8mm

Material of taping is paper

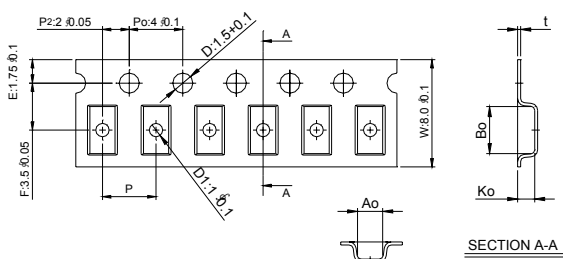


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03



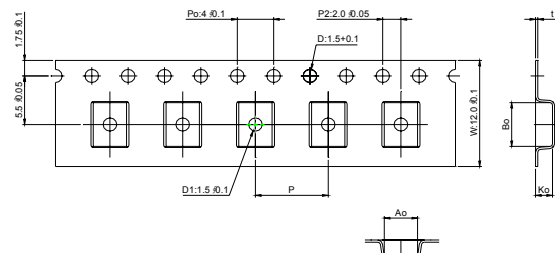
Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321611	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm

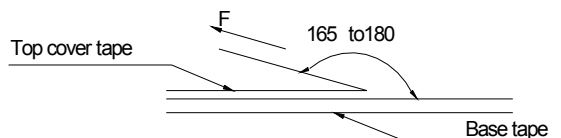


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

7-3. Packaging Quantity

Chip Size	453215	451616	322513	321611	321609	201212	201209	160808	100505
Chip / Reel	1000	2000	2500	3000	3000	2000	4000	4000	10000
Inner box	4000	8000	12500	15000	15000	10000	20000	20000	50000
Middle box	20000	40000	62500	75000	75000	50000	100000	100000	250000
Carton	40000	80000	125000	150000	150000	100000	200000	200000	500000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
 - To maintain the solder ability of terminal electrodes:
 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
 3. Recommended products should be used within 12 months from the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 1 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

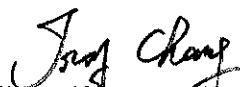
(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description) : FERRITE CHIP BEAD、FERRITE CHIP INDUCTOR、ARRAY、MCF、MCM、YMV、APM SERIES
樣品型號(Style/Item No.) : FERRITE CHIP BEAD、FERRITE CHIP INDUCTOR、ARRAY、MCF、MCM、YMV、APM SERIES
收件日期(Sample Receiving Date) : 2019/12/04
測試期間(Testing Period) : 2019/12/04 to 2019/12/10

測試結果(Test Results) : 請參閱下一頁 (Please refer to following pages).


Troy Chang / Manager - Tec
Signed for and behalf of
SGS TAIWAN LTD.
Chemical Laboratory - Taipei



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



測試報告

Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 2 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗區嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANGSU ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No. 1 : 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
鎘 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013), 以感應耦合電漿發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-OES.	2	n. d.
鉛 / Lead (Pb)	mg/kg		2	n. d.
汞 / Mercury (Hg)	mg/kg		2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	參考IEC 62321-7-2 (2017), 以UV-VIS檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.	8	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg	參考IEC 62321-6 (2015), 以氣相層析/質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	5	n. d.	

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

SGS Taiwan Ltd. 台灣檢驗科技股份有限公司

25, Wu Chuan 7th Road, New Taipei Industrial Park, Wu Ku District, New Taipei City, Taiwan / 新北市五股區新北產業園區五權七路25號
t+886 (02)2299 3939 f+886 (02)2299 3237 www.sgs.com.tw

Member of the SGS Group



測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 3 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	參考IEC 62321-6 (2015), 以氣相層析/ 質譜儀檢測。 / With reference to IEC 62321-6 (2015) and performed by GC/MS.	-	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg	5	n. d.	
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α -HBCDD, β -HBCDD, γ -HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008), 以氣相層析/ 質譜儀檢測。 / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.
鹵素 / Halogen				
鹵素(氟) / Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	參考BS EN 14582 (2016), 以離子層析儀 分析。 / With reference to BS EN 14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(氯) / Halogen-Chlorine (Cl) (CAS No.: 22537-15-1)	mg/kg		50	n. d.
鹵素(溴) / Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg		50	n. d.
鹵素(碘) / Halogen-Iodine (I) (CAS No.: 14362-44-8)	mg/kg		50	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

SGS Taiwan Ltd. 台灣檢驗科技股份有限公司

25, Wu Chuan 7th Road, New Taipei Industrial Park, Wu Ku District, New Taipei City, Taiwan / 新北市五股區新北產業園區五權七路25號
t+886 (02)2299 3939 f+886 (02)2299 3237 www.sgs.com.tw

Member of the SGS Group



測試報告

Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 4 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗區嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No. : 85-68-7)	mg/kg	參考IEC 62321-8 (2017), 以氣相層析/質譜儀檢測。 / With reference to IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No. : 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二(2-乙基己基)酯 / DEHP (Di-(2-ethylhexyl) phthalate) (CAS No. : 117-81-7)	mg/kg		50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No. : 84-69-5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di-isodecyl phthalate) (CAS No. : 26761-40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di-isononyl phthalate) (CAS No. : 28553-12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No. : 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No. : 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / DNPP (Di-n-pentyl phthalate) (CAS No. : 131-18-0)	mg/kg		50	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	參考US EPA 3550C (2007), 以液相層析/質譜儀檢測。 / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n. d.
全氟辛酸 / PFOA (CAS No. : 335-67-1)	mg/kg		10	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告

Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 5 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
				No. 1
銻 / Antimony (Sb)	mg/kg	參考US EPA 3052 (1996), 以感應耦合電漿發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-OES.	2	n. d.
鈹 / Beryllium (Be)	mg/kg		2	n. d.
砷 / Arsenic (As)	mg/kg		2	n. d.
聚氯乙烯 / Polyvinyl chloride (PVC)	**	以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test.	-	Negative

備註(Note) :

1. mg/kg = ppm; 0.1wt% = 1000ppm
2. MDL = Method Detection Limit (方法偵測極限值)
3. n. d. = Not Detected (未檢出)
4. "-" = Not Regulated (無規格值)
5. **= Qualitative analysis (No Unit) 定性分析(無單位)
6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)
7. 樣品的測試是基於申請人要求混合測試, 報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS參考資訊(Reference Information) : 持久性有機污染物 POPs - (EU) 2019/1021

PFOS濃度在物質或製備中不得超過0.001%(10ppm), 在半成品、成品或零部件中不得超過0.1%(1000ppm), 在紡織品或塗層材料中不得超過1µg/m²。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above 1µg/m².)

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 6 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

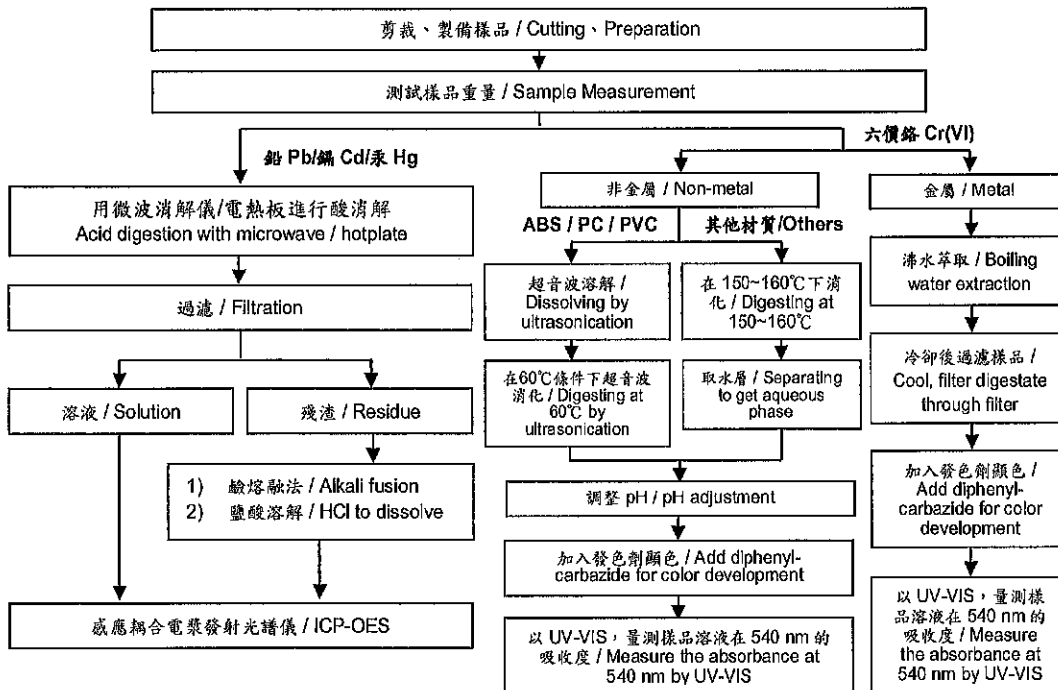
(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件, 樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)

- 測試人員: 陳恩臻 / Technician: Rita Chen
- 測試負責人: 張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/terms-and-conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 7 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

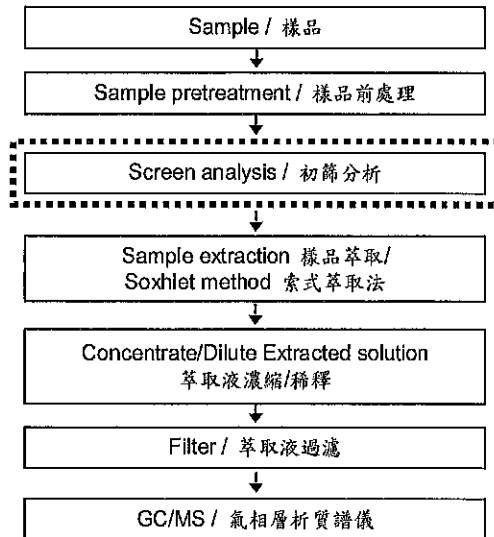
多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

- 測試人員: 涂雅苓 / Technician: Yaling Tu
- 測試負責人: 張啟興 / Supervisor: Troy Chang

初次測試程序 / First testing process —————>

選擇性篩檢程序 / Optional screen process>

確認程序 / Confirmation process - - ->



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 8 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

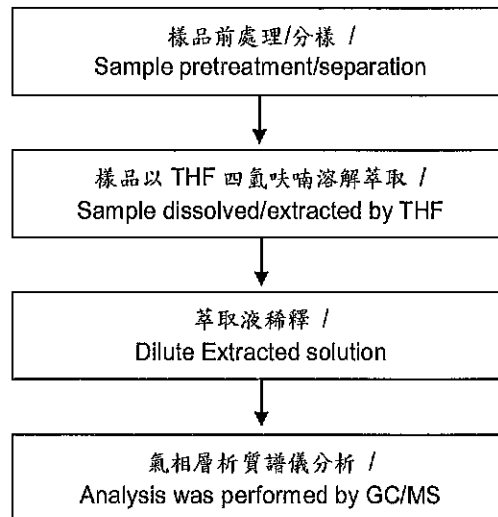
(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

可塑劑分析流程圖 / Analytical flow chart - Phthalate

- 測試人員：涂雅苓 / Technician: Yaling Tu
- 測試負責人：張啟興 / Supervisor: Troy Chang

【測試方法/Test method: IEC 62321-8】



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 9 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

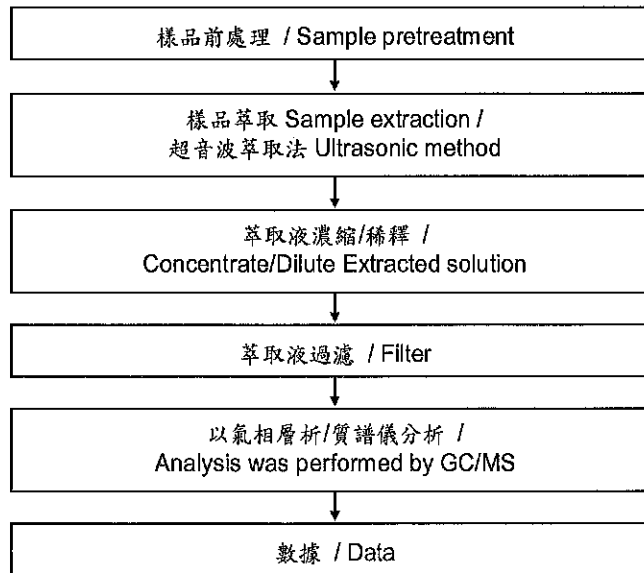
桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員：涂雅苓 / Technician: Yaling Tu
- 測試負責人：張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/terms-and-conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 10 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

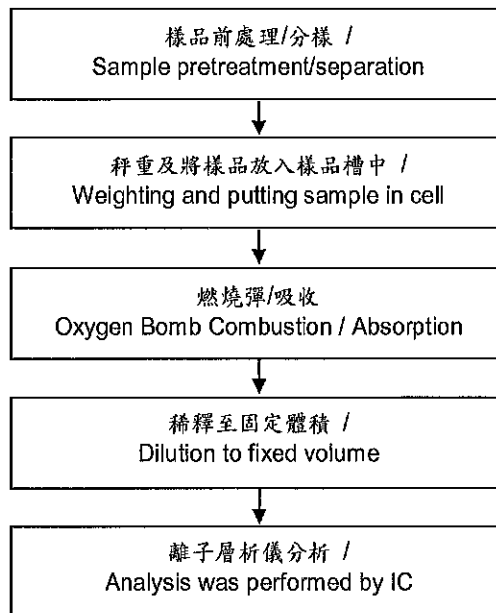
桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

鹵素分析流程圖 / Analytical flow chart - Halogen

- 測試人員：陳恩臻 / Technician: Rita Chen
- 測試負責人：張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/terms-and-conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 11 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

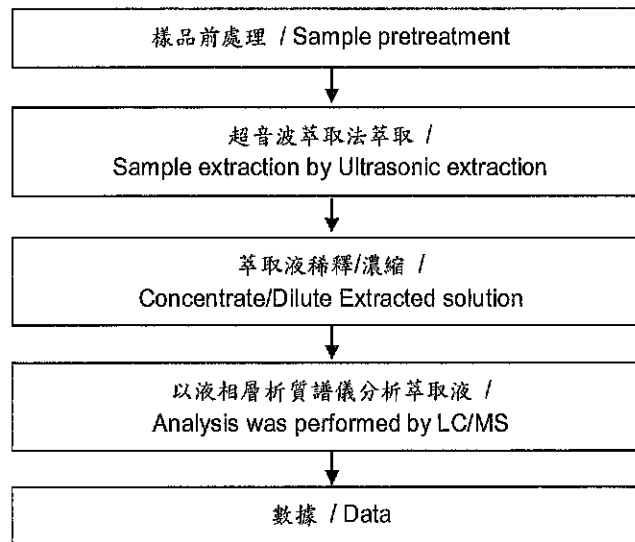
桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

全氟辛酸/全氟辛酸磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS

- 測試人員: 涂雅苓 / Technician: Yaling Tu
- 測試負責人: 張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 12 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

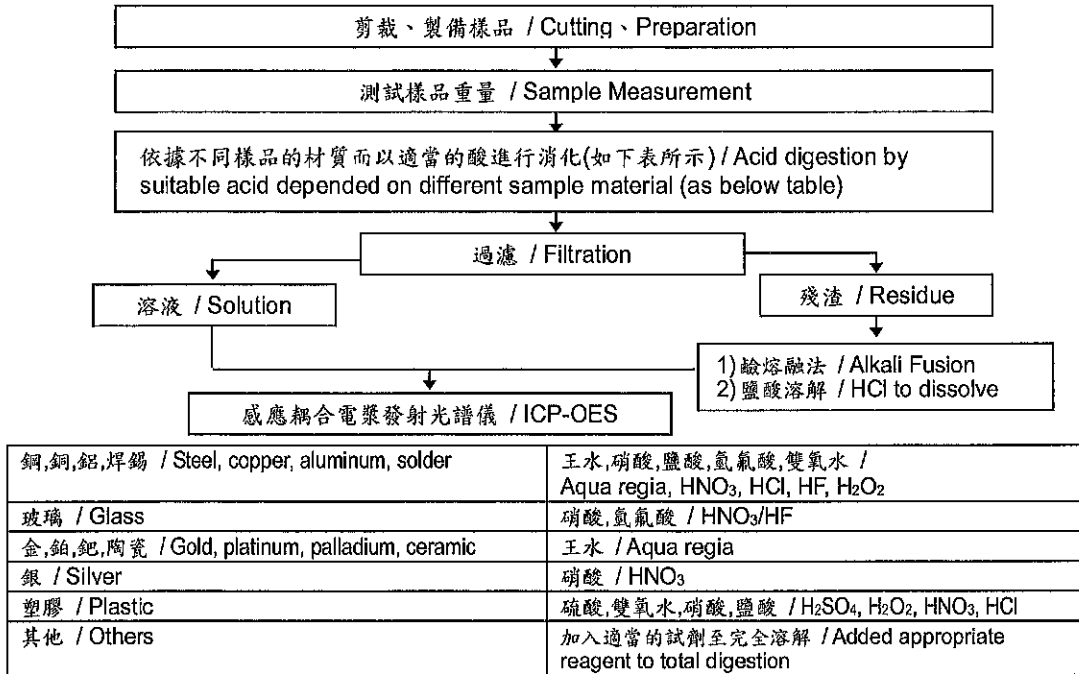
(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANGSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

根據以下的流程圖之條件, 樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員: 陳恩臻 / Technician: Rita Chen
- 測試負責人: 張啟興 / Supervisor: Troy Chang

元素以 ICP-OES 分析的消化流程圖
(Flow Chart of digestion for the elements analysis performed by ICP-OES)



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/terms-and-conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 13 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

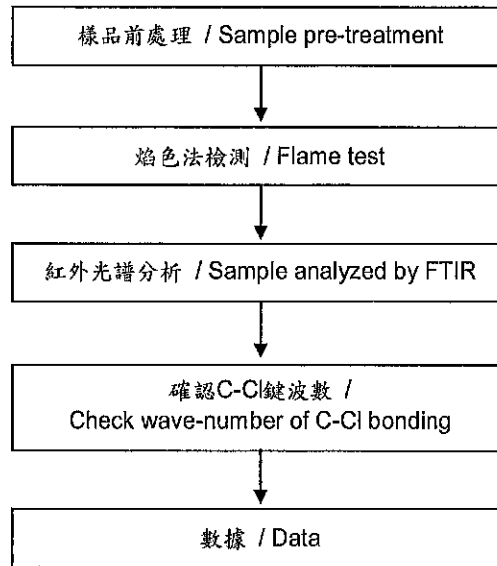
桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC

- 測試人員：涂雅琴 / Technician: Yaling Tu
- 測試負責人：張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/Terms-and-Conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

測試報告 Test Report

號碼(No.) : CE/2019/C0498

日期(Date) : 2019/12/10

頁數(Page): 14 of 14

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

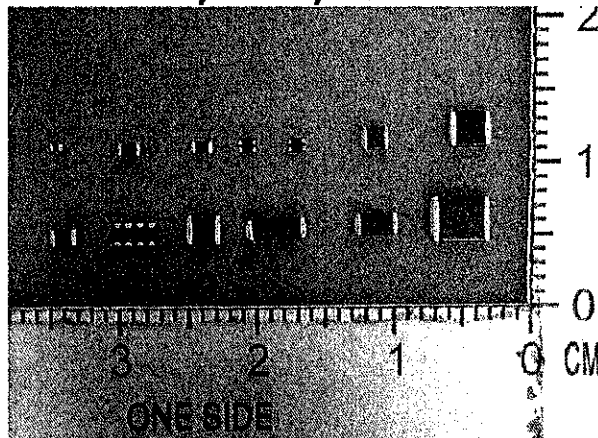
(江蘇省昆山市蓬朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國, 江蘇省, 宿遷市, 泗洪縣, 經濟開發區杭州路南側, 建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

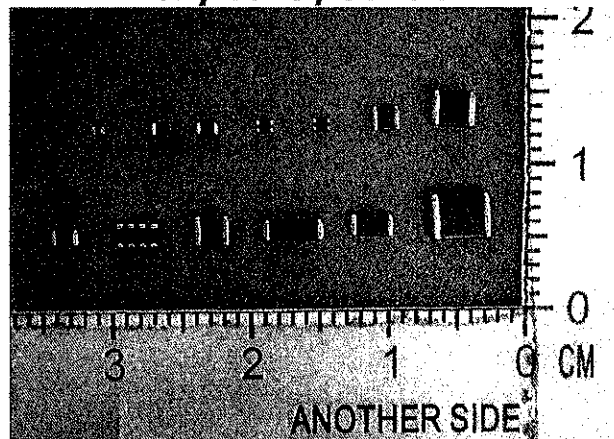
* 照片中如有箭頭標示, 則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2019/C0498



CE/2019/C0498



** 報告結尾 (End of Report) **

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <http://www.sgs.com/en/terms-and-conditions.aspx> and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <https://www.sgs.com/en/terms-and-conditions/terms-e-document>. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.

单击下面可查看定价，库存，交付和生命周期等信息

[>>TAI-TECH\(台庆\)](#)